			DB	Time stamp
L Number	Hits	<pre>Search Text ((((((((((((conduct\$3 copper) near5 (foil</pre>	USPAT;	2003/04/29 18:26
1	2856	sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	-333, 33, 23 23 23
		(via trench hole recess)) and (insulat\$3	00 10111	j
		dielectric)) and (pr photo?resist		/
		photoresist resist)) and (copper Cu		
		aluminum Al)) and wir\$3) and resin) and		
		circuit) and (cover\$3 encapsulat\$3)) and		[
		((etch\$3 pattern\$4) near10 (copper Cu	/	ĺ
	-	conduct\$3))) and wir\$3) and (die bond\$3)	EPO; JPO;	2003/04/29 18:27
2	5	<pre>(((((((((((((conduct\$3 copper) near5 (foil sheet layer) ) and (etch\$3 pattern\$4)) and</pre>	DERWENT;	2003/01/23 1012/
		(via trench hole recess)) and (insulat\$3	IBM TDB	
		dielectric)) and (pr photo?resist	_	
		photoresist resist)) and (copper Cu		
		aluminum Al)) and wir\$3) and resin) and	ĺ	
]		circuit) and (cover\$3 encapsulat\$3)) and		
		((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)		
3	5	(((((((((((conduct\$3 copper) near5 (foil	EPO; JPO;	2003/04/29 18:28
]		sheet layer plate) ) and (etch\$3	DERWENT;	
		<pre>pattern\$4)) and (via trench hole recess))</pre>	IBM_TDB	,
}		and (insulat\$3 dielectric)) and (pr		
[		photo?resist photoresist resist)) and	į	
		(copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)		
		near10 (copper Cu conduct\$3))) and wir\$3)		
}		and (die bond\$3)		
4	2908	(((((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/04/29 18:29
		sheet layer plate) ) and (etch\$3	US-PGPUB	
i l		<pre>pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr</pre>		
		photo?resist photoresist resist)) and		
		(copper Cu aluminum Al)) and wir\$3) and		
		resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)		
		near10 (copper Cu conduct\$3))) and wir\$3)		
		and (die bond\$3)	HCDAT.	2003/04/29 18:30
5	52	<pre>(((((((((((((conduct\$3 copper) near5 (foil sheet layer plate) ) and (etch\$3</pre>	USPAT; US-PGPUB	2003/04/29 10.30
		pattern\$4)) and (via trench hole recess))	00 10100	
		and (insulat\$3 dielectric)) and (pr		
		photo?resist photoresist resist)) and		
		(copper Cu aluminum Al)) and wir\$3) and		
		resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)   near10 (copper Cu conduct\$3))) and wir\$3)		
1		and (die bond\$3)) not		,
		((((((((((((conduct\$3 copper) near5		
{		(foil sheet layer) ) and (etch\$3		
		pattern\$4)) and (via trench hole recess))		
		and (insulat\$3 dielectric)) and (pr		
		photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and		
1		resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)		
		near10 (copper Cu conduct\$3))) and wir\$3)		
		and (die bond\$3))		
-	12192	conduct\$3 near5 foil	USPAT;	2003/02/11 15:12
	4707	/acaduah63 manuf fail) and manin	US-PGPUB USPAT;	2003/02/11 12:50
-	4707	(conduct\$3 near5 foil) and resin	US-PGPUB	2003/02/11 12.50
_	3142	((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:51
		(pattern\$5 etch\$3)	US-PGPUB	
-	2706	(((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:51
		(pattern\$5 etch\$3)) and (insulat\$3	US-PGPUB	
_	2520	dielectric)   ((((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:53
-	2530	((((conduct\$3 near5 foil) and resin) and (pattern\$5 etch\$3)) and (insulat\$3	US-PGPUB	2003/02/11 12.33
		dielectric)   and (via hole recess contact)	00 10100	
L	L	d201000110// d1.0 (1.11 11010 100000 00110000/	L	

-	968	(((((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:53
	}	(pattern\$5 etch\$3)) and (insulat\$3	US-PGPUB	j j
		dielectric)) and (via hole recess		
1		contact)) and (pr resist)	HODAM	2003/02/11 12:54
-	755	(((((conduct\$3 near5 foil) and resin) and	USPAT	2003/02/11 12.54
		(pattern\$5 etch\$3)) and (insulat\$3	}	
		dielectric)) and (via hole recess		
1	445	contact)) and (pr resist) multilayer\$3 near3 wir\$3 near3 circuit	USPAT;	2003/02/11 13:02
_	445	multilayers hears wirs hears circuit	US-PGPUB	2000, 02, 22 2010
	183779	(conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:16
-	103/19	layer)	US-PGPUB	
_	111368	((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:18
	121000	laver) ) and (etch\$3 pattern\$4)	US-PGPUB	
-	80228	(((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:30
		layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	
	İ	trench hole recess)		
-	67836	((((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:31
	1	layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	1
		trench hole recess)) and (insulat\$3		
		dielectric)	rianam.	2003/02/11 15:32
] -	30233	(((((conduct\$3 copper) near5 (foil sheet	USPAT; US-PGPUB	2003/02/11 13:32
		layer) ) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3	US-FGFUB	1
	]	dielectric)) and (pr photo?resist	,	}
İ	1	photoresist resist)		
	28811	((((((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:34
1	20011	layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	
ļ	Į.	trench hole recess)) and (insulat\$3		
		dielectric)) and (pr photo?resist		
1	1	photoresist resist)) and (copper Cu		
		aluminum Al)	ļ	
-	13674		USPAT;	2003/02/11 15:35
		layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	
		trench hole recess)) and (insulat\$3		1
		dielectric)) and (pr photo?resist	1	
1	(	photoresist resist)) and (copper Cu		
ļ	5200	aluminum Al)) and wir\$3 (((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 15:39
1 -	5322	sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	2003/02/11 13:33
		(via trench hole recess)) and (insulat\$3	05 10105	
		dielectric)) and (pr photo?resist		
		photoresist resist)) and (copper Cu		J
		aluminum Al)) and wir\$3) and resin		
_	834	((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 16:35
		sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
	1	(via trench hole recess)) and (insulat\$3	1	
		dielectric)) and (pr photo?resist		
1	1	photoresist resist)) and (copper Cu	1	
	İ	aluminum Al)) and wir\$3) and resin) and	1	
1		(singulat\$3 dic\$3)	IICDAM:	2003/02/11 16:36
-	4670	((((((((conduct\$3 copper) near5 (foil	USPAT; US-PGPUB	2003/02/11 10:30
1	1	sheet layer) ) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3	US-FGFUD	
		dielectric)) and (pr photo?resist		
		photoresist resist)) and (copper Cu	1	
		aluminum Al)) and wir\$3) and resin) and		
	1	circuit	<b>f</b>	
-	4040	((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 16:37
		sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
		(via trench hole recess)) and (insulat\$3	}	
		dielectric)) and (pr photo?resist		
}		photoresist resist)) and (copper Cu	1	
		aluminum Al)) and wir\$3) and resin) and	1	
	<u></u>	circuit) and (cover\$3 encapsulat\$3)	L	L,

- 3307 (((((((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (US-PGPUB (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu	7:36
(via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and	
dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and	
photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and	
aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and	
circuit) and (cover\$3 encapsulat\$3)) and	
((etch\$3 pattern\$4) near10 (copper Cu	J
conduct\$3))	
- 3307 (((((((((((conduct\$3 copper) near5 (foil   USPAT;   2003/02/11 17	:36
sheet layer) ) and (etch\$3 pattern\$4)) and   US-PGPUB	
(via trench hole recess)) and (insulat\$3	į
dielectric)) and (pr photo?resist	
photoresist resist)) and (copper Cu	
aluminum Al)) and wir\$3) and resin) and	
circuit) and (cover\$3 encapsulat\$3)) and	1
((etch\$3 pattern\$4) near10 (copper Cu	İ
conduct\$3))) and wir\$3	
- 2618 ((((((((((((((((((((((((((((((((((((	:39
sheet layer) ) and (etch\$3 pattern\$4)) and   US-PGPUB	
(via trench hole recess)) and (insulat\$3	
dielectric)) and (pr photo?resist	
photoresist resist)) and (copper Cu	1
aluminum Al)) and wir\$3) and resin) and	
circuit) and (cover\$3 encapsulat\$3)) and	
((etch\$3 pattern\$4) near10 (copper Cu	
conduct\$3))) and wir\$3) and bond\$3	)
- 2660 ((((((((((((((((((((((((((((((((((	:42
sheet layer) ) and (etch\$3 pattern\$4)) and US-PGPUB	]
(via trench hole recess)) and (insulat\$3	į
dielectric)) and (pr photo?resist	ļ
photoresist resist)) and (copper Cu	j
aluminum Al)) and wir\$3) and resin) and	
circuit) and (cover\$3 encapsulat\$3)) and	Ì
((etch\$3 pattern\$4) near10 (copper Cu	
conduct\$3))) and wir\$3) and (die bond\$3)	

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